

Amendments to the Specification

IN THE TITLE

Please change USPTO records to indicate that the title to be used in this application is ---ELECTROLESS COPPER PLATING SOLUTION AND ELECTROLESS COPPER PLATING METHOD---, which title coincides with the title appearing in the English translation of the specification.

IN THE WRITTEN DESCRIPTION

Please replace paragraph [0008] with the following amended paragraph:

[0008]

Specifically, the present invention is as follows.

(1) An electroless copper plating ~~solution~~method, wherein, ~~along with a first reducing agent, using an electroless copper plating solution comprising~~ hypophosphorous acid or a hypophosphite is used as a second reducing agent, ~~and a stabilizer to inhibit copper deposition is further used at the same time along with a first reducing agent and further comprising a stabilizer to inhibit copper deposition at the same time, a mirror surface whose average surface roughness is less than 10 nm is electroless plated to produce a thin film with a thickness of 500 nm or less.~~

(2) An electroless copper plating ~~solution~~method according to (1) above, ~~which is used to produce a thin film with a thickness of 500 nm or less wherein a pretreatment agent is prepared by reacting or mixing in advance a noble metal compound and a silane coupling agent having a functional group with metal capturing capability, and said mirror surface is treated with the pretreatment agent.~~

(3) An electroless copper plating method, ~~wherein an electroless copper plating solution according to (1) or (2) above is used to perform electroless copper plating on a mirror surface whose average surface roughness is less than 10 nm, wherein the first reducing agent is glyoxylic acid, the second reducing agent is hypophosphorous acid and the stabilizer to inhibit copper deposition is 2,2'-bipyridyl.~~